

QuickSpec Terminal Soldering Compliance Guide

IPC Class Three Specifications

synopsis of select class 3 specifications please see current revision of IPC-A-610 for more details



Training Center



All Terminals

- Solder fillet min 75% of wire/lead and teminal interface
- Solder height greater than 50% wire diameter
- Wire/lead discernable in solder joint
- Wires are mechanically secure before soldering
- Solder wetted min 75% of contact area if wrap180 deg or more
- Solder wetted 100% for wraps less than 180 deg





Turrett

- wire wrapped a min 180 deg and not overlap itself
- I wire end can not overlap itself



Hook

- Wires wrapped at least 180 deg
- No overlap of wire turns
- Min 1 wire diamter from end of hook to the closest wire



Bifurcated Side Mount

- Wire passes through slot and makes positive contact with at least one corner post & no portion of wire above top of terminal
- Wire wrap at least 90 deg
- **Bottom and Top Mount**
- Wire insulation can not enter base
- # Bottom route contacts 2 parallel sides of post
- Wire against base of terminal
- Top route has space filled with filler wire

Cup

- Wire inserted full depth of cup
- Wire in contact with back wall
- Wire not modified to fit connector
- Multiple conductors not twisted together
- Thin film of solder on outside of cup
- Solder fill 75% or more
- Solder buildup on outside cup does not affect form fit or function









Pierced/perforated/punched Wire passes through eye Wire wrapped to contact opposite side

